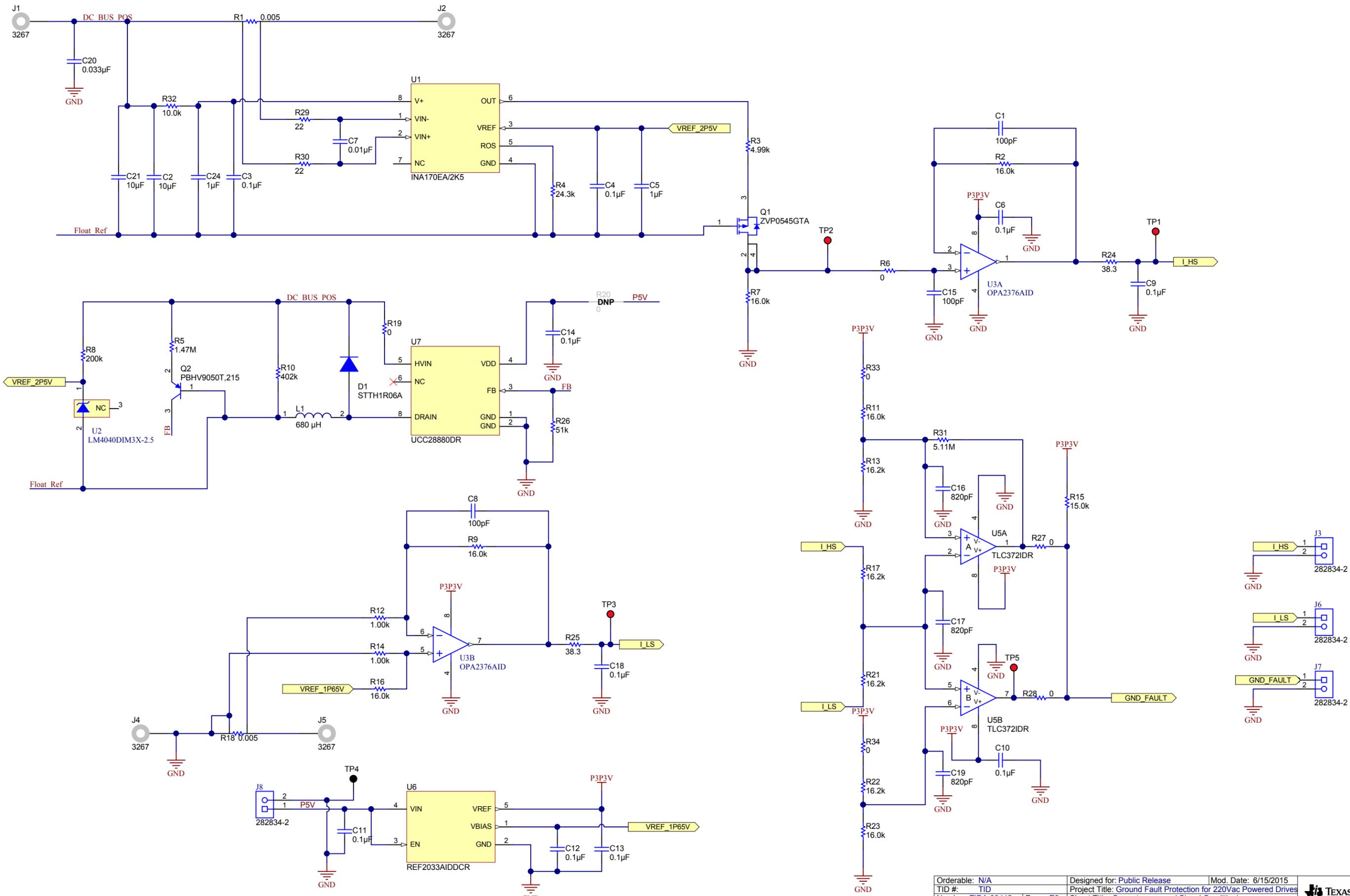


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TID #: TID	Project Title: Ground Fault Protection for 220Vac Powered Drives		
Number: TIDA-00442	Rev: E2	Sheet Title: Block Diagram	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By: Pawan N	File: Sh01_CoverSheet.SchDoc	Size: B	
Engineer: Pawan N	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



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TID #: TID	Project Title: Ground Fault Protection for 220Vac Powered Drives	
Number: TIDA-00442	Rev: E2	Sheet Title: Current sense and Signal Conditioning
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: Pawan N	File: Sh02_Current_sense.SchDoc	Size: B
Engineer: Pawan N	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



H1 NY PMS 440 0025 PH    H2 NY PMS 440 0025 PH    H3 NY PMS 440 0025 PH    H4 NY PMS 440 0025 PH

FID1    FID2    FID3    FID4    FID5    FID6

PCB Number: TIDA-00442  
PCB Rev: E2

PCB  
LOGO  
Texas Instruments

LBL1  
PCB Label  
Size: 0.65" x 0.20"

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TID	Project Title: Ground Fault Protection for 220Vac Powered Drives		
Number: TIDA-00442	Rev: E2	Sheet: 3 of 3	
SVN Rev: Version control disabled	Assembly Variant: 001	File: Sh03_TID_Hardware.SchDoc	
Drawn By: Pawan N	Engineer: Pawan N	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Size: B

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